

# CLEANING LABORATORY EVALUATION SUMMARY

SCL #: 2002

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ClientType: Electronics Manufacturer

ProjectNumber: Project #1

Substrates: Stainless Steel, Steel

PartType: Coupon

Contaminants: Adhesive, Cutting/Tapping Fluids, Lubricating/Lapping Oils, Oil

Cleaning Methods: Plasma

Analytical Methods: Gravimetric

Purpose: To evaluate plasma cleaning for parts cleaning

Experimental Procedure: Chamber with a plate in it to put coupons on. The plate can be heated or left at ambient. We will run experiments at ambient. This technology is generally used to clean computer wafers and is done at approximately 250 C  
 The process is done in a vacuum with plasma that can consist of gases such as O2, NF3, CF4, N2H2 and Argon. We will use mainly O2 gas plasma. The plasma is pumped into the chamber and when it reacts with the organic contaminants a blue glow can be seen. When all the organics are oxidized the glow is purple (pure O2 plasma). Want to use or test organic contaminants that contain H, C, O etc. Things such as lipids and metals are hard to remove with this process. Their chemical structure would deter or inhibit cleaning.

Contaminants:  
 Company Product Composition  
 Solutia Inc. Gelva Multipolymer Resin Solution 2895 Resin solid: 50862-46-9  
 Ethyl Acetate: 141-78-6  
 Heptane: 142-82-5  
 Isopropyl Alcohol: 67-63-0  
 Ethanol: 64-17-5  
 Vinyl Acetate: 108-05-4  
 Bencyn, Inc. B-5186, Metal Working Compound Hydrotreated Heavy Napthenic Distillate: 64742-52-5  
 Polyisobutene: 9003-29-6  
 Aliphatic Alkyl Phosphate: 3946469-2  
 Acrylic Copolymer: 63197-48-8  
 The Valvoline Co. Tectyl 505, Petroleum Based Rust Preventative Aliphatic Hydrocarbon: 8052-41-3

Results: Trial 1. O2 plasma, Valvoline contaminant, steel coupons ( #'s 12, 13, 14)  
 Flow rate of O2 plasma was 300 cc/min  
 Temp on plate reading 18 C  
 Vp in chamber from contaminant was 0.04 T (0.03T when all valves open and 0.07 T when shut. Difference in Vp can be contributed to contaminant)  
 Pressure .19T  
 Power 300 Watts  
 Time 5 minutes  
 Stopped flow after 5 minutes. Opened valves and flushed out chamber (no vacuum). Temp on plate reading 21 C ( 2 degree increased in plate temp due to reaction and plasma flow)

2. Same coupons, same conditions for 5 more minutes.  
 Only difference end temperature after this 5 minutes was 25 C @ atmospheric pressure

3. O2 & N2H2 plasma, Valvoline contaminant, steel coupons ( #'s 16, 17, 18)  
 Flow rate 500 cc/min O2, 70 cc/min N2H2  
 Pressure .26T  
 Power 500 Watts  
 Time 5 minutes  
 When stopped flow temperature at 30 C. Open valve and purge chamber and temp reads 33 C @ atmospheric pressure

4. O2 plasma, Solutia, Inc, Gelva Mulipolymer Resin 2815, stainless steel coupons ( #'s 6,7,8)  
 Flow rate of O2 plasma was 300 cc/min  
 Pressure .19T  
 Power 300 Watts  
 Time 5 minutes  
 Stopped flow after 5 minutes. Opened valves and flushed out chamber (no vacuum). Temp on plate reading 27 C @ atmospheric pressure  
 This contaminant also visibly changed. Looks bubbly?

5. Same coupons as in 4 for another 5 minutes

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6. O2 plasma, Bencyn, Inc B-5186, Stainless steel coupons (#'s 21, 22, 23)

Flow rate of O2 plasma was 300 cc/min

Pressure .19T

Power 300 Watts

Time 5 minutes

Stopped flow after 5 minutes. Opened valves and flushed out chamber (no vacuum). Temp on plate reading 31 C @ atmospheric pressure

This contaminant also visibly changed to a yellow color from a brown color

7. O2 plasma, one coupon of each contaminant, Stainless steel (#'s 15, 16, 27 )

Temperature 50 C

Power 500 Watts

Flow rate O2 plasma 500 cc/min

Pressure .19T

(Increase Temp, Pressure and Power)

8. O2, CF4 plasma, one coupon of each contaminant, (#'s 17, 11, 24)

Temperature 50 C

Power 500 Watts

Flow rate O2 plasma 500 cc/min, CF4 50 cc/min

Pressure .19T

(Increase Temp, Pressure, Power and change composition of plasma)

Trial #	1	2	3	4	5	6	7
Plasma Type	O2	O2	O2 & N2H2	O2	O2	O2	O2
Cleaner	Valvoline 5	Valvoline 10	Valvoline 5	Gelva 5	Gelva 10	Bencyn 5	Bencyn 10
Coupon 1	42.16	27.56	59.86	18.45	4.16	7.50	1.69
Coupon 2	35.11	19.70	52.55	18.26	3.40	4.43	2.60
Coupon 3	30.86	15.91	56.03	16.72	3.38	2.97	1.84
Ave	36.04	21.06	56.15	17.81	3.65	4.96	2.04
Std Dev	5.71	5.94	3.65	0.95	0.45	2.31	0.49
Total	57.10			21.46		7.01	

Trial 8

	Valvoline	Gelva	Bencyn
Increase Flow & temp	38.97	22.28	9.33
Increase Flow & temp w CH4	27.72	21.89	8.09

Summary:

<b>Substrates:</b>	Stainless Steel, Steel				
<b>Contaminants:</b>	Adhesive, Cutting/Tapping Fluids, Lubricating/Lapping Oils, Oil				
<b>Company Name:</b>	<b>Product Name:</b>	<b>Conc.:</b>	<b>Efficiency:</b>	<b>Effective:</b>	<b>Observations:</b>
No Specific Vendor	Oxygen Plasma	100	36.04	<input type="checkbox"/>	Valvoline 5
No Specific Vendor	Oxygen Plasma	100	57.10	<input type="checkbox"/>	Valvoline 10 (total)
No Specific Vendor	O2 & N2H2 Plasma	100	56.15	<input type="checkbox"/>	Valvoline 5
No Specific Vendor	Oxygen Plasma	100	17.81	<input type="checkbox"/>	Gelva 5
No Specific Vendor	Oxygen Plasma	100	21.46	<input type="checkbox"/>	Gelva 10 (total)
No Specific Vendor	Oxygen Plasma	100	4.96	<input type="checkbox"/>	Bencyn 5
No Specific Vendor	Oxygen Plasma	100	7.01	<input type="checkbox"/>	Bencyn 10 (total)

Conclusion:

Questions to answer:

Not very good cleaning efficiencies. Are we just baking the contaminant or removing? Evaluate back at lab. Fluorine may increase cleaning efficiencies. DO NOT WANT TO USE due to money and chemical issues. Water addition to decrease ashing and lift more contaminant off? Decrease pressure not increase?